

SEMICONDUCTOR PACKAGE INCLUDING STACKED CHIPS

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ABSTRACT OF THE DISCLOSURE

Semiconductor packages are disclosed. An exemplary package includes horizontal leads each having a first side and an opposite second side. The second side includes a recessed horizontal surface. Two stacked semiconductor chips are within the package and are electrically interconnected in a flip chip style. One chip extends over the first side of the leads and is electrically connected thereto. The chips are encapsulated in a package body formed of an encapsulating material. The recessed horizontal surface of the leads is covered by the encapsulating material, and a portion of the second side of each lead is exposed at an exterior surface of the package body as an input/output terminal. A surface of one or both chips may be exposed. The stack of chips may be supported on the first side of the leads or on a chip mounting plate.

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